

## QUADRUPLE DIFFERENTIAL LINE DRIVER

### FEATURES

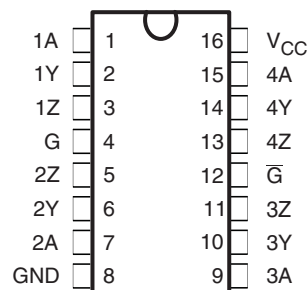
- Meets or Exceeds the Requirements of TIA/EIA-422-B and ITU Recommendation V.11
- Low Power,  $I_{CC} = 100 \mu A$  Typ
- Operates From a Single 5-V Supply
- High Speed,  $t_{PLH} = t_{PHL} = 7 \text{ ns}$  Typ
- Low Pulse Distortion,  $t_{sk(p)} = 0.5 \text{ ns}$  Typ
- High Output Impedance in Power-Off Conditions
- Improved Replacement for AM26LS31
- Available in Q-Temp Automotive
  - High-Reliability Automotive Applications
  - Configuration Control/Print Support
  - Qualification to Automotive Standards

### DESCRIPTION/ORDERING INFORMATION

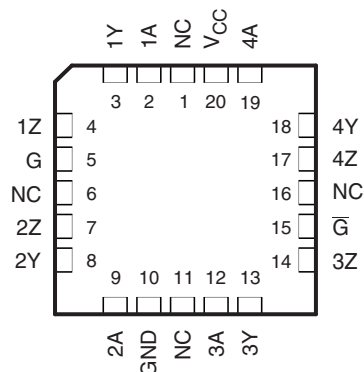
The AM26C31 is a differential line driver with complementary outputs, designed to meet the requirements of TIA/EIA-422-B and ITU (formerly CCITT). The 3-state outputs have high-current capability for driving balanced lines, such as twisted-pair or parallel-wire transmission lines, and they provide the high-impedance state in the power-off condition. The enable functions are common to all four drivers and offer the choice of an active-high (G) or active-low ( $\bar{G}$ ) enable input. BiCMOS circuitry reduces power consumption without sacrificing speed.

The AM26C31C is characterized for operation from 0°C to 70°C, the AM26C31I is characterized for operation from –40°C to 85°C, the AM26C31Q is characterized for operation over the automotive temperature range of –40°C to 125°C, and the AM26C31M is characterized for operation over the full military temperature range of –55°C to 125°C.

AM26C31M...J OR W PACKAGE  
AM26C31Q...D PACKAGE  
AM26C31C...D, DB, OR NS PACKAGE  
AM26C31I...D, DB, N, NS, OR PW PACKAGE  
(TOP VIEW)



AM26C31M...FK PACKAGE  
(TOP VIEW)



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**ORDERING INFORMATION**

| <b>T<sub>A</sub></b> | <b>PACKAGE<sup>(1)(2)</sup></b> |              | <b>ORDERABLE PART NUMBER</b> | <b>TOP-SIDE MARKING</b> |
|----------------------|---------------------------------|--------------|------------------------------|-------------------------|
| 0°C to 70°C          | PDIP (N)                        | Tube of 25   | AM26C31CN                    | AM26C31CN               |
|                      | SOIC (D)                        | Tube of 40   | AM26C31CD                    | AM26C31C                |
|                      |                                 | Reel of 2500 | AM26C31CDR                   |                         |
|                      | SOP (NS)                        | Reel of 2000 | AM26C31CNSR                  | 26C31                   |
|                      | SSOP (DB)                       | Reel of 2000 | AM26C31CDBR                  | 26C31                   |
| –40°C to 85°C        | PDIP (N)                        | Tube of 25   | AM26C31IN                    | AM26C31IN               |
|                      | SOIC (D)                        | Tube of 40   | AM26C31ID                    | AM26C31I                |
|                      |                                 | Reel of 2500 | AM26C31IDR                   |                         |
|                      | SOP (NS)                        | Reel of 2000 | AM26C31INSR                  | 26C31I                  |
|                      | SSOP (DB)                       | Reel of 2000 | AM26C31IDBR                  | 26C31I                  |
|                      | TSSOP (PW)                      | Tube of 90   | AM26C31IPW                   | 26C31I                  |
| –40°C to 125°C       | SOIC (D)                        | Tube of 40   | AM26C31QD                    | AM26C31QD               |
|                      |                                 | Reel of 2500 | AM26C31QDR                   |                         |
| –55°C to 125°C       | CDIP (J)                        | Tube of 25   | AM26C31MJ                    | AM26C31MJ               |
|                      | CFP (W)                         | Tube of 150  | AM26C31MW                    | AM26C31MW               |
|                      | LCCC (FK)                       | Tube of 55   | AM26C31MFK                   | AM26C31MFK              |

(1) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

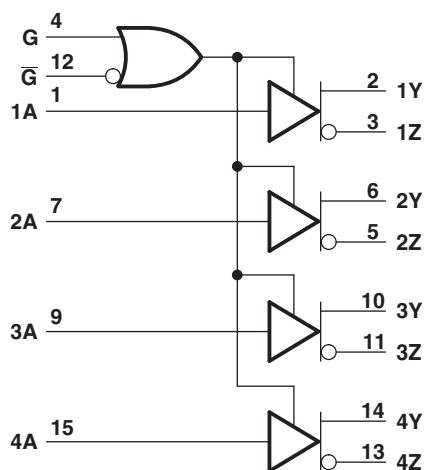
(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).

**FUNCTION TABLE  
(Each Driver)<sup>(1)</sup>**

| <b>INPUT<br/>A</b> | <b>ENABLES</b> |                                  | <b>OUTPUTS</b> |          |
|--------------------|----------------|----------------------------------|----------------|----------|
|                    | <b>G</b>       | <b><math>\overline{G}</math></b> | <b>Y</b>       | <b>Z</b> |
| H                  | H              | X                                | H              | L        |
| L                  | H              | X                                | L              | H        |
| H                  | X              | L                                | H              | L        |
| L                  | X              | L                                | L              | H        |
| X                  | L              | H                                | Z              | Z        |

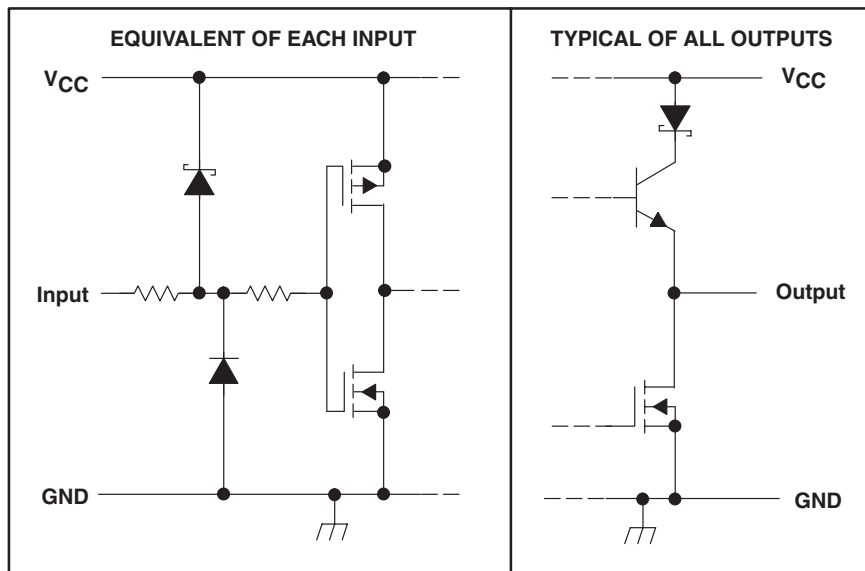
(1) H = High level, L = Low level, X = Irrelevant,  
Z = High impedance (off)

### LOGIC DIAGRAM (POSITIVE LOGIC)



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

### SCHEMATICS OF INPUTS AND OUTPUTS



**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

|                      |                                             | MIN        | MAX            | UNIT |
|----------------------|---------------------------------------------|------------|----------------|------|
| $V_{CC}$             | Supply voltage range <sup>(2)</sup>         | –0.5       | 7              | V    |
| $V_I$                | Input voltage range                         | –0.5       | $V_{CC} + 0.5$ | V    |
| $V_{ID}$             | Differential input voltage range            | –14        | 14             | V    |
| $V_O$                | Output voltage range                        | –0.5       | 7              |      |
| $I_{IK}$<br>$I_{OK}$ | Input or output clamp current               |            | ±20            | mA   |
| $I_O$                | Output current                              |            | ±150           | mA   |
|                      | $V_{CC}$ current                            |            | 200            | mA   |
|                      | GND current                                 | –200       |                | mA   |
| $\theta_{JA}$        | Package thermal impedance <sup>(3)(4)</sup> | D package  | 73             | °C/W |
|                      |                                             | DB package | 82             |      |
|                      |                                             | N package  | 67             |      |
|                      |                                             | NS package | 64             |      |
|                      |                                             | PW package | 108            |      |
| $T_J$                | Operating virtual junction temperature      |            | 150            | °C   |
| $T_{stg}$            | Storage temperature range                   | –65        | 150            | °C   |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to the network ground terminal.
- (3) Maximum power dissipation is a function of  $T_{J(max)}$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_{J(max)} - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

**RECOMMENDED OPERATING CONDITIONS**

|          |                                | MIN      | NOM | MAX | UNIT |
|----------|--------------------------------|----------|-----|-----|------|
| $V_{CC}$ | Supply voltage                 | 4.5      | 5   | 5.5 | V    |
| $V_{ID}$ | Differential input voltage     |          | ±7  |     | V    |
| $V_{IH}$ | High-level input voltage       | 2        |     |     | V    |
| $V_{IL}$ | Low-level input voltage        |          |     | 0.8 | V    |
| $I_{OH}$ | High-level output current      |          |     | –20 | μA   |
| $I_{OL}$ | Low-level output current       |          |     | 20  | mA   |
| $T_A$    | Operating free-air temperature | AM26C31C | 0   | 70  | °C   |
|          |                                | AM26C31I | –40 | 85  |      |
|          |                                | AM26C31Q | –40 | 125 |      |
|          |                                | AM26C31M | –55 | 125 |      |

## ELECTRICAL CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER           |                                                                   | TEST CONDITIONS                                | AM26C31C<br>AM26C31I |                    |      | UNIT |
|---------------------|-------------------------------------------------------------------|------------------------------------------------|----------------------|--------------------|------|------|
|                     |                                                                   |                                                | MIN                  | TYP <sup>(1)</sup> | MAX  |      |
| V <sub>OH</sub>     | High-level output voltage                                         | I <sub>O</sub> = –20 mA                        | 2.4                  | 3.4                |      | V    |
| V <sub>OL</sub>     | Low-level output voltage                                          | I <sub>O</sub> = 20 mA                         |                      | 0.2                | 0.4  | V    |
| V <sub>OD</sub>     | Differential output voltage magnitude                             | R <sub>L</sub> = 100 Ω, See Figure 1           | 2                    | 3.1                |      | V    |
| Δ V <sub>OD</sub>   | Change in magnitude of differential output voltage <sup>(2)</sup> | R <sub>L</sub> = 100 Ω, See Figure 1           |                      |                    | ±0.4 | V    |
| V <sub>OC</sub>     | Common-mode output voltage                                        | R <sub>L</sub> = 100 Ω, See Figure 1           |                      |                    | 3    | V    |
| Δ V <sub>OC</sub>   | Change in magnitude of common-mode output voltage <sup>(2)</sup>  | R <sub>L</sub> = 100 Ω, See Figure 1           |                      |                    | ±0.4 | V    |
| I <sub>I</sub>      | Input current                                                     | V <sub>I</sub> = V <sub>CC</sub> or GND        |                      |                    | ±1   | μA   |
| I <sub>O(off)</sub> | Driver output current with power off                              | V <sub>CC</sub> = 0                            |                      |                    | 100  | μA   |
|                     |                                                                   | V <sub>O</sub> = 6 V                           |                      |                    | –100 | μA   |
|                     |                                                                   | V <sub>O</sub> = –0.25 V                       |                      |                    |      |      |
| I <sub>OS</sub>     | Driver output short-circuit current                               | V <sub>O</sub> = 0                             | –30                  |                    | –150 | mA   |
| I <sub>OZ</sub>     | High-impedance off-state output current                           | V <sub>O</sub> = 2.5 V                         |                      |                    | 20   | μA   |
|                     |                                                                   | V <sub>O</sub> = 0.5 V                         |                      |                    | –20  | μA   |
| I <sub>CC</sub>     | Quiescent supply current                                          | I <sub>O</sub> = 0                             |                      |                    | 100  | μA   |
|                     |                                                                   | V <sub>I</sub> = 0 or 5 V                      |                      |                    |      |      |
|                     |                                                                   | V <sub>I</sub> = 2.4 V or 0.5 V <sup>(3)</sup> |                      | 1.5                | 3    | mA   |
| C <sub>i</sub>      | Input capacitance                                                 |                                                |                      | 6                  |      | pF   |

(1) All typical values are at V<sub>CC</sub> = 5 V and T<sub>A</sub> = 25°C.

(2) Δ|V<sub>OD</sub>| and Δ|V<sub>OC</sub>| are the changes in magnitude of V<sub>OD</sub> and V<sub>OC</sub>, respectively, that occur when the input is changed from a high level to a low level.

(3) This parameter is measured per input. All other inputs are at 0 or 5 V.

## SWITCHING CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER                               |                                                            | TEST CONDITIONS            | AM26C31C<br>AM26C31I |                    |     | UNIT |
|-----------------------------------------|------------------------------------------------------------|----------------------------|----------------------|--------------------|-----|------|
|                                         |                                                            |                            | MIN                  | TYP <sup>(1)</sup> | MAX |      |
| t <sub>PLH</sub>                        | Propagation delay time, low-to-high-level output           | S1 is open, See Figure 2   | 3                    | 7                  | 12  | ns   |
| t <sub>PHL</sub>                        | Propagation delay time, high-to-low-level output           |                            | 3                    | 7                  | 12  |      |
| t <sub>sk(p)</sub>                      | Pulse skew time ( t <sub>PLH</sub> – t <sub>PHL</sub>  )   | S1 is open, See Figure 2   |                      | 0.5                | 4   | ns   |
| t <sub>r(OD)</sub> , t <sub>f(OD)</sub> | Differential output rise and fall times                    | S1 is open, See Figure 3   |                      | 5                  | 10  | ns   |
| t <sub>PZH</sub>                        | Output enable time to high level                           | S1 is closed, See Figure 4 |                      | 10                 | 19  | ns   |
| t <sub>PZL</sub>                        | Output enable time to low level                            |                            |                      | 10                 | 19  |      |
| t <sub>PHZ</sub>                        | Output disable time from high level                        | S1 is closed, See Figure 4 |                      | 7                  | 16  | ns   |
| t <sub>PLZ</sub>                        | Output disable time from low level                         |                            |                      | 7                  | 16  |      |
| C <sub>pd</sub>                         | Power dissipation capacitance (each driver) <sup>(2)</sup> | S1 is open, See Figure 2   |                      | 170                |     | pF   |

(1) All typical values are at V<sub>CC</sub> = 5 V and T<sub>A</sub> = 25°C.

(2) C<sub>pd</sub> is used to estimate the switching losses according to P<sub>D</sub> = C<sub>pd</sub> × V<sub>CC</sub><sup>2</sup> × f, where f is the switching frequency.

## ELECTRICAL CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER           |                                                                   | TEST CONDITIONS                                | AM26C31Q<br>AM26C31M |                    |      | UNIT |
|---------------------|-------------------------------------------------------------------|------------------------------------------------|----------------------|--------------------|------|------|
|                     |                                                                   |                                                | MIN                  | TYP <sup>(1)</sup> | MAX  |      |
| V <sub>OH</sub>     | High-level output voltage                                         | I <sub>O</sub> = –20 mA                        | 2.2                  | 3.4                |      | V    |
| V <sub>OL</sub>     | Low-level output voltage                                          | I <sub>O</sub> = 20 mA                         |                      | 0.2                | 0.4  | V    |
| V <sub>OD</sub>     | Differential output voltage magnitude                             | R <sub>L</sub> = 100 Ω, See Figure 1           | 2                    | 3.1                |      | V    |
| Δ V <sub>OD</sub>   | Change in magnitude of differential output voltage <sup>(2)</sup> | R <sub>L</sub> = 100 Ω, See Figure 1           |                      |                    | ±0.4 | V    |
| V <sub>OC</sub>     | Common-mode output voltage                                        | R <sub>L</sub> = 100 Ω, See Figure 1           |                      |                    | 3    | V    |
| Δ V <sub>OC</sub>   | Change in magnitude of common-mode output voltage <sup>(2)</sup>  | R <sub>L</sub> = 100 Ω, See Figure 1           |                      |                    | ±0.4 | V    |
| I <sub>I</sub>      | Input current                                                     | V <sub>I</sub> = V <sub>CC</sub> or GND        |                      |                    | ±1   | μA   |
| I <sub>O(off)</sub> | Driver output current with power off                              | V <sub>CC</sub> = 0                            |                      |                    | 100  | μA   |
|                     |                                                                   | V <sub>O</sub> = 6 V                           |                      |                    | –100 | μA   |
|                     |                                                                   | V <sub>O</sub> = –0.25 V                       |                      |                    |      |      |
| I <sub>OS</sub>     | Driver output short-circuit current                               | V <sub>O</sub> = 0                             |                      |                    | –170 | mA   |
| I <sub>OZ</sub>     | High-impedance off-state output current                           | V <sub>O</sub> = 2.5 V                         |                      |                    | 20   | μA   |
|                     |                                                                   | V <sub>O</sub> = 0.5 V                         |                      |                    | –20  | μA   |
| I <sub>CC</sub>     | Quiescent supply current                                          | I <sub>O</sub> = 0                             |                      |                    | 100  | μA   |
|                     |                                                                   | V <sub>I</sub> = 0 or 5 V                      |                      |                    |      |      |
|                     |                                                                   | V <sub>I</sub> = 2.4 V or 0.5 V <sup>(3)</sup> |                      |                    | 3.2  | mA   |
| C <sub>i</sub>      | Input capacitance                                                 |                                                |                      |                    | 6    | pF   |

(1) All typical values are at V<sub>CC</sub> = 5 V and T<sub>A</sub> = 25°C.

(2) Δ|V<sub>OD</sub>| and Δ|V<sub>OC</sub>| are the changes in magnitude of V<sub>OD</sub> and V<sub>OC</sub>, respectively, that occur when the input is changed from a high level to a low level.

(3) This parameter is measured per input. All other inputs are at 0 or 5 V.

## SWITCHING CHARACTERISTICS

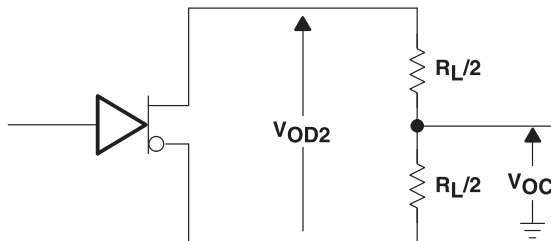
over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER                               |                                                            | TEST CONDITIONS            | AM26C31Q<br>AM26C31M |                    |     | UNIT |
|-----------------------------------------|------------------------------------------------------------|----------------------------|----------------------|--------------------|-----|------|
|                                         |                                                            |                            | MIN                  | TYP <sup>(1)</sup> | MAX |      |
| t <sub>PLH</sub>                        | Propagation delay time, low-to-high-level output           | S1 is open, See Figure 2   |                      | 7                  | 12  | ns   |
| t <sub>PHL</sub>                        | Propagation delay time, high-to-low-level output           |                            |                      | 6.5                | 12  |      |
| t <sub>sk(p)</sub>                      | Pulse skew time ( t <sub>PLH</sub> – t <sub>PHL</sub>  )   | S1 is open, See Figure 2   |                      | 0.5                | 4   | ns   |
| t <sub>r(OD)</sub> , t <sub>f(OD)</sub> | Differential output rise and fall times                    | S1 is open, See Figure 3   |                      | 5                  | 12  | ns   |
| t <sub>PZH</sub>                        | Output enable time to high level                           | S1 is closed, See Figure 4 |                      | 10                 | 19  | ns   |
| t <sub>PZL</sub>                        | Output enable time to low level                            |                            |                      | 10                 | 19  |      |
| t <sub>PHZ</sub>                        | Output disable time from high level                        | S1 is closed, See Figure 4 |                      | 7                  | 16  | ns   |
| t <sub>PLZ</sub>                        | Output disable time from low level                         |                            |                      | 7                  | 16  |      |
| C <sub>pd</sub>                         | Power dissipation capacitance (each driver) <sup>(2)</sup> | S1 is open, See Figure 2   |                      | 100                |     | pF   |

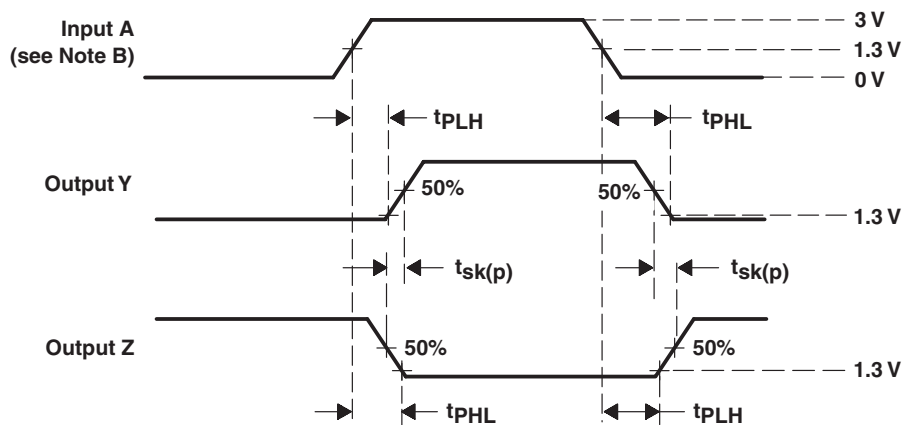
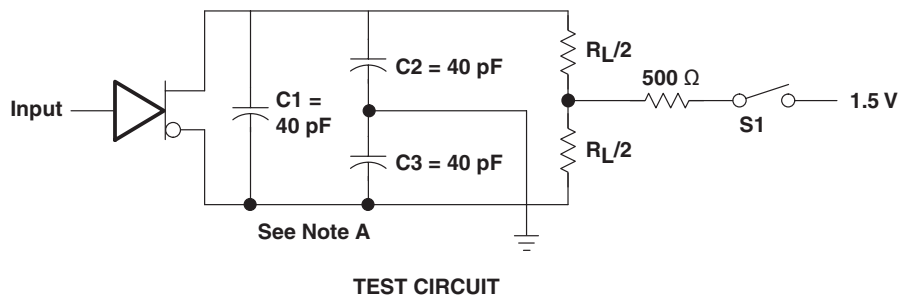
(1) All typical values are at V<sub>CC</sub> = 5 V and T<sub>A</sub> = 25°C.

(2) C<sub>pd</sub> is used to estimate the switching losses according to P<sub>D</sub> = C<sub>pd</sub> × V<sub>CC</sub><sup>2</sup> × f, where f is the switching frequency.

## PARAMETER MEASUREMENT INFORMATION



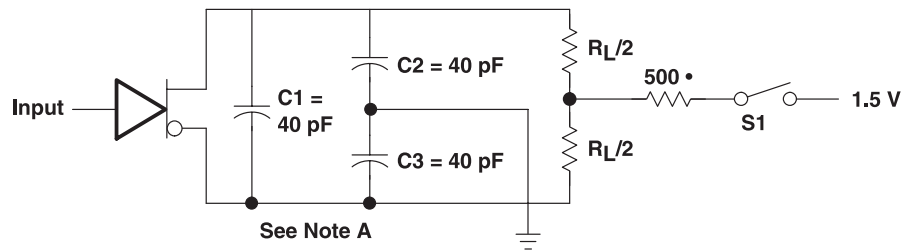
**Figure 1. Differential and Common-Mode Output Voltages**



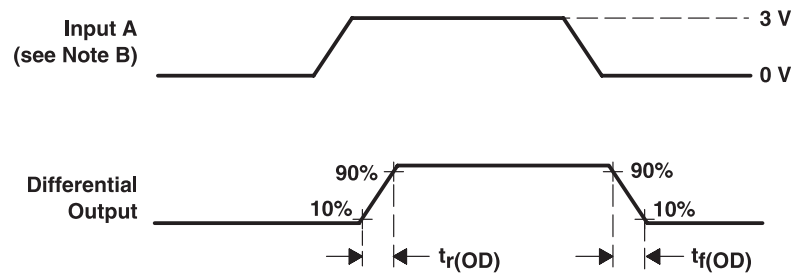
- A. C1, C2, and C3 include probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, duty cycle  $\leq$  50%, and  $t_r$ ,  $t_f \leq$  6 ns.

**Figure 2. Propagation Delay Time and Skew Waveforms and Test Circuit**

## PARAMETER MEASUREMENT INFORMATION (continued)



TEST CIRCUIT

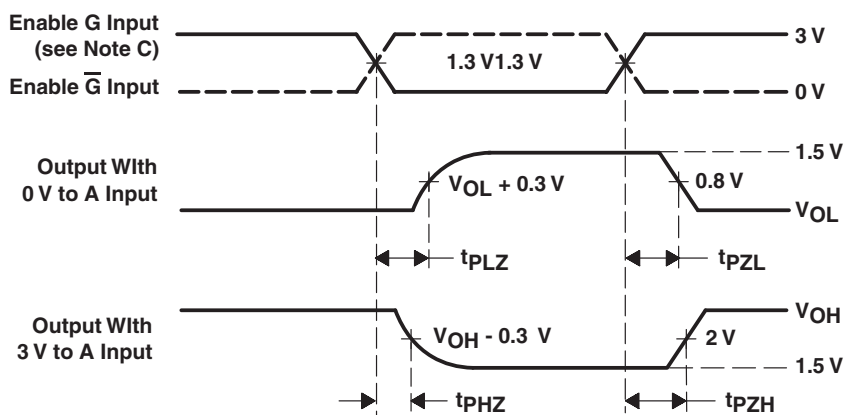
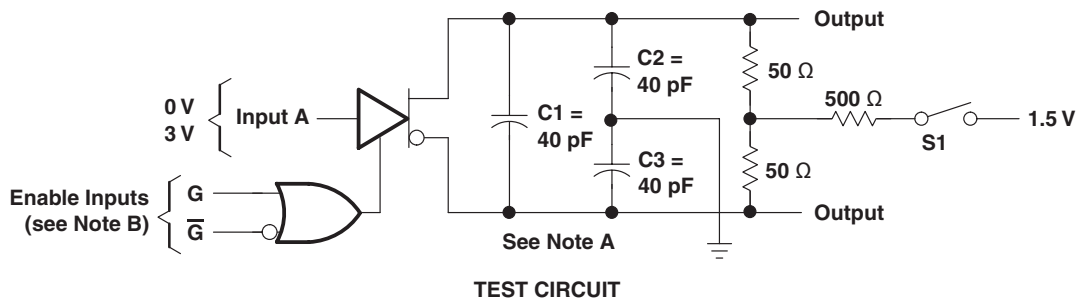


VOLTAGE WAVEFORMS

- A. C1, C2, and C3 include probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics:  $\text{PRR} \leq 1 \text{ MHz}$ , duty cycle  $\leq 50\%$ , and  $t_r, t_f \leq 6 \text{ ns}$ .

**Figure 3. Differential-Output Rise- and Fall-Time Waveforms and Test Circuit**

## PARAMETER MEASUREMENT INFORMATION (continued)



- A. C1, C2, and C3 include probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ , duty cycle  $\leq 50\%$ , and  $t_r, t_f \leq 6 \text{ ns}$ .
- C. Each enable is tested separately.

**Figure 4. Output Enable- and Disable-Time Waveforms and Test Circuit**

## TYPICAL CHARACTERISTICS

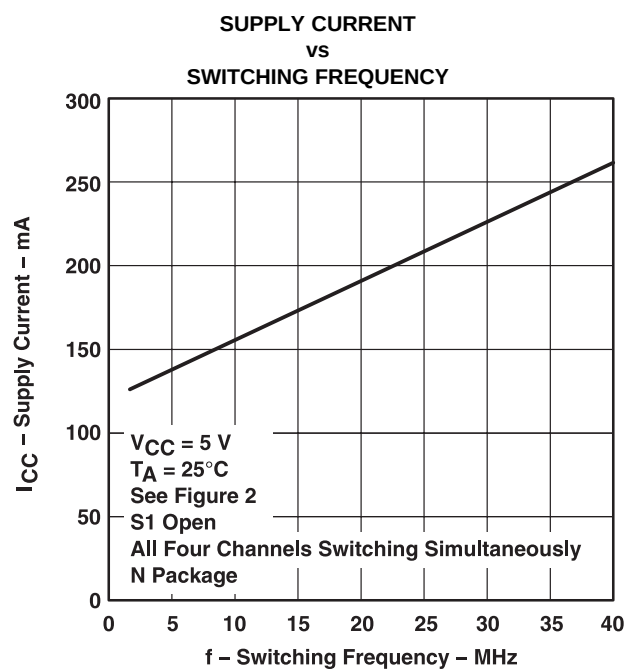


Figure 5.

**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/Ball Finish | MSL Peak Temp <sup>(3)</sup> |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| AM26C31CD        | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31CDBLE     | OBSOLETE              | SSOP         | DB              | 16   |             | TBD                     | Call TI          | Call TI                      |
| AM26C31CDBR      | ACTIVE                | SSOP         | DB              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31CDBRE4    | ACTIVE                | SSOP         | DB              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31CDBRG4    | ACTIVE                | SSOP         | DB              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31CDE4      | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31CDG4      | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31CDR       | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31CDRE4     | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31CDRG4     | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31CN        | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| AM26C31CNE4      | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| AM26C31CNSR      | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31CNSRE4    | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31CNSRG4    | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31ID        | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IDBLE     | OBSOLETE              | SSOP         | DB              | 16   |             | TBD                     | Call TI          | Call TI                      |
| AM26C31IDBR      | ACTIVE                | SSOP         | DB              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IDBRE4    | ACTIVE                | SSOP         | DB              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IDBRG4    | ACTIVE                | SSOP         | DB              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IDE4      | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IDG4      | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IDR       | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IDRE4     | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IDRG4     | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IN        | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free                 | CU NIPDAU        | N / A for Pkg Type           |

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/Ball Finish | MSL Peak Temp <sup>(3)</sup> |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| (RoHS)           |                       |              |                 |      |             |                         |                  |                              |
| AM26C31INE4      | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | N / A for Pkg Type           |
| AM26C31INSR      | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31INSRG4    | ACTIVE                | SO           | NS              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IPW       | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IPWE4     | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IPWG4     | ACTIVE                | TSSOP        | PW              | 16   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IPWR      | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31IPWRG4    | ACTIVE                | TSSOP        | PW              | 16   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31QD        | ACTIVE                | SOIC         | D               | 16   | 40          | TBD                     | CU NIPDAU        | Level-1-220C-UNLIM           |
| AM26C31QDG4      | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| AM26C31QDR       | ACTIVE                | SOIC         | D               | 16   | 2500        | TBD                     | CU NIPDAU        | Level-1-220C-UNLIM           |
| AM26C31QDRG4     | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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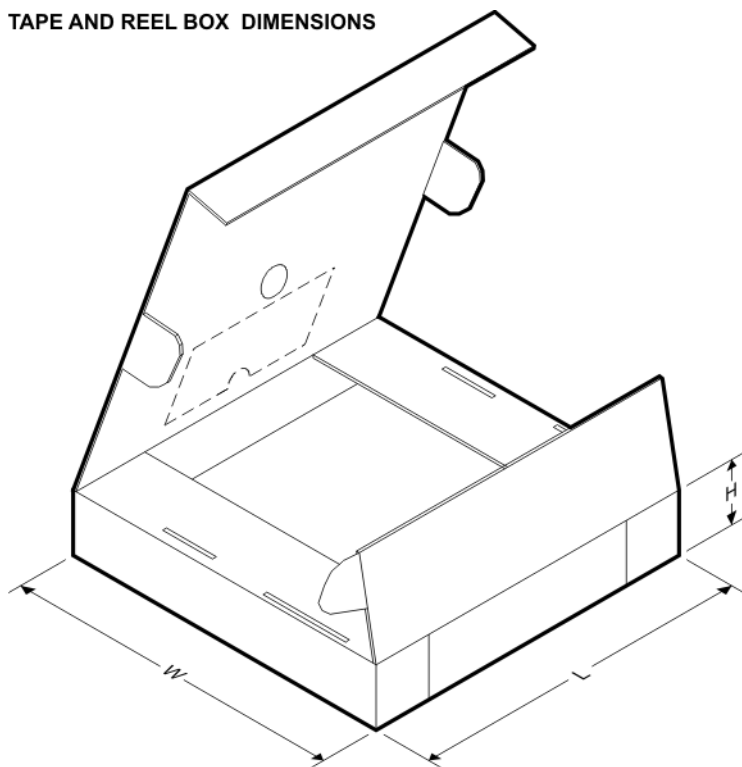
**TAPE AND REEL INFORMATION**



\*All dimensions are nominal

| Device      | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| AM26C31CDBR | SSOP         | DB              | 16   | 2000 | 330.0              | 16.4               | 8.2     | 6.6     | 2.5     | 12.0    | 16.0   | Q1            |
| AM26C31CDR  | SOIC         | D               | 16   | 2500 | 330.0              | 16.4               | 6.5     | 10.3    | 2.1     | 8.0     | 16.0   | Q1            |
| AM26C31CNSR | SO           | NS              | 16   | 2000 | 330.0              | 16.4               | 8.2     | 10.5    | 2.5     | 12.0    | 16.0   | Q1            |
| AM26C31IDBR | SSOP         | DB              | 16   | 2000 | 330.0              | 16.4               | 8.2     | 6.6     | 2.5     | 12.0    | 16.0   | Q1            |
| AM26C31IDR  | SOIC         | D               | 16   | 2500 | 330.0              | 16.4               | 6.5     | 10.3    | 2.1     | 8.0     | 16.0   | Q1            |
| AM26C31INSR | SO           | NS              | 16   | 2000 | 330.0              | 16.4               | 8.2     | 10.5    | 2.5     | 12.0    | 16.0   | Q1            |
| AM26C31IPWR | TSSOP        | PW              | 16   | 2000 | 330.0              | 12.4               | 7.0     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

| Device      | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|
| AM26C31CDBR | SSOP         | DB              | 16   | 2000 | 346.0       | 346.0      | 33.0        |
| AM26C31CDR  | SOIC         | D               | 16   | 2500 | 333.2       | 345.9      | 28.6        |
| AM26C31CNSR | SO           | NS              | 16   | 2000 | 346.0       | 346.0      | 33.0        |
| AM26C31IDBR | SSOP         | DB              | 16   | 2000 | 346.0       | 346.0      | 33.0        |
| AM26C31IDR  | SOIC         | D               | 16   | 2500 | 333.2       | 345.9      | 28.6        |
| AM26C31INSR | SO           | NS              | 16   | 2000 | 346.0       | 346.0      | 33.0        |
| AM26C31IPWR | TSSOP        | PW              | 16   | 2000 | 346.0       | 346.0      | 29.0        |

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## PW (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

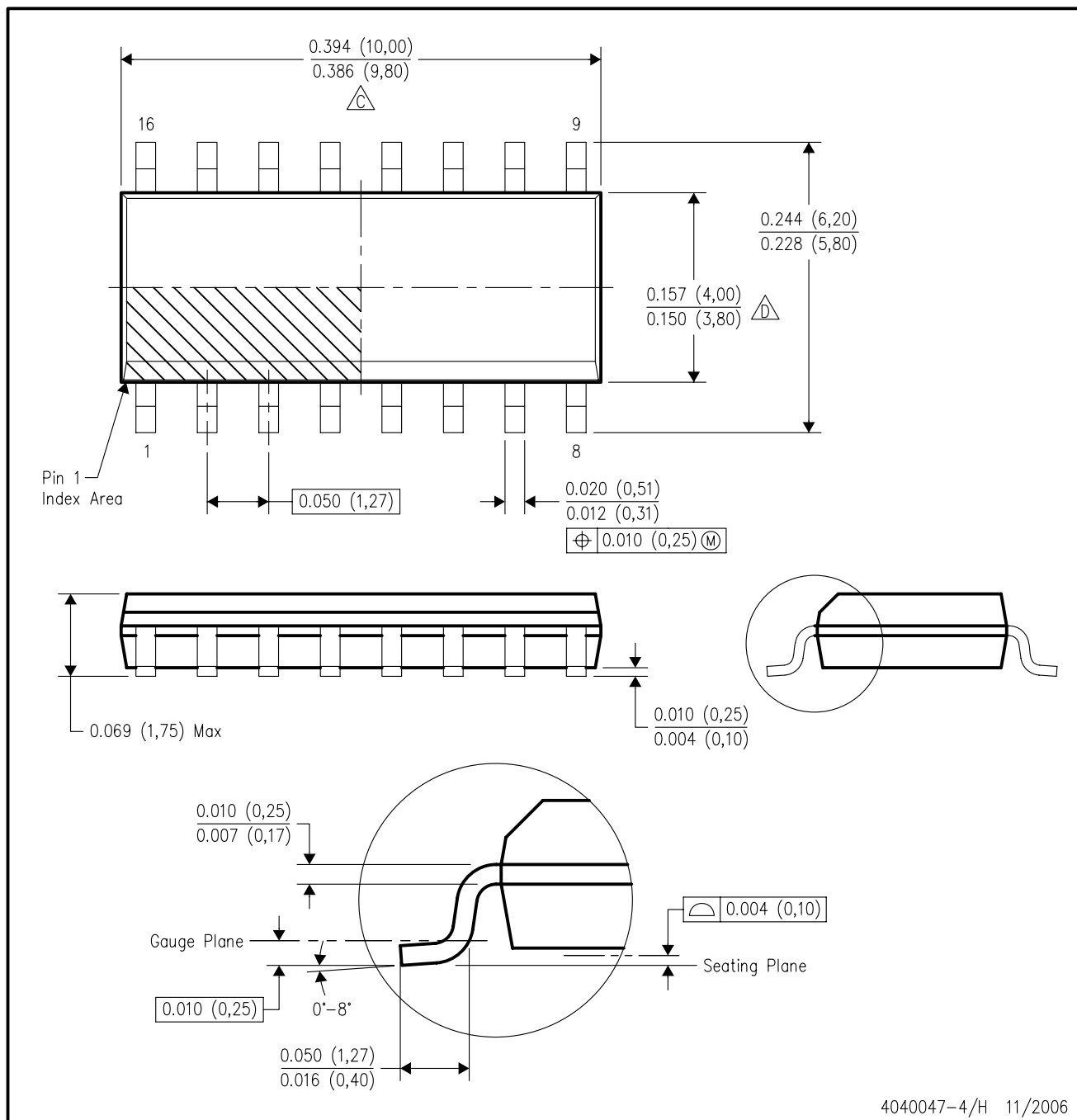
14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

## D (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE

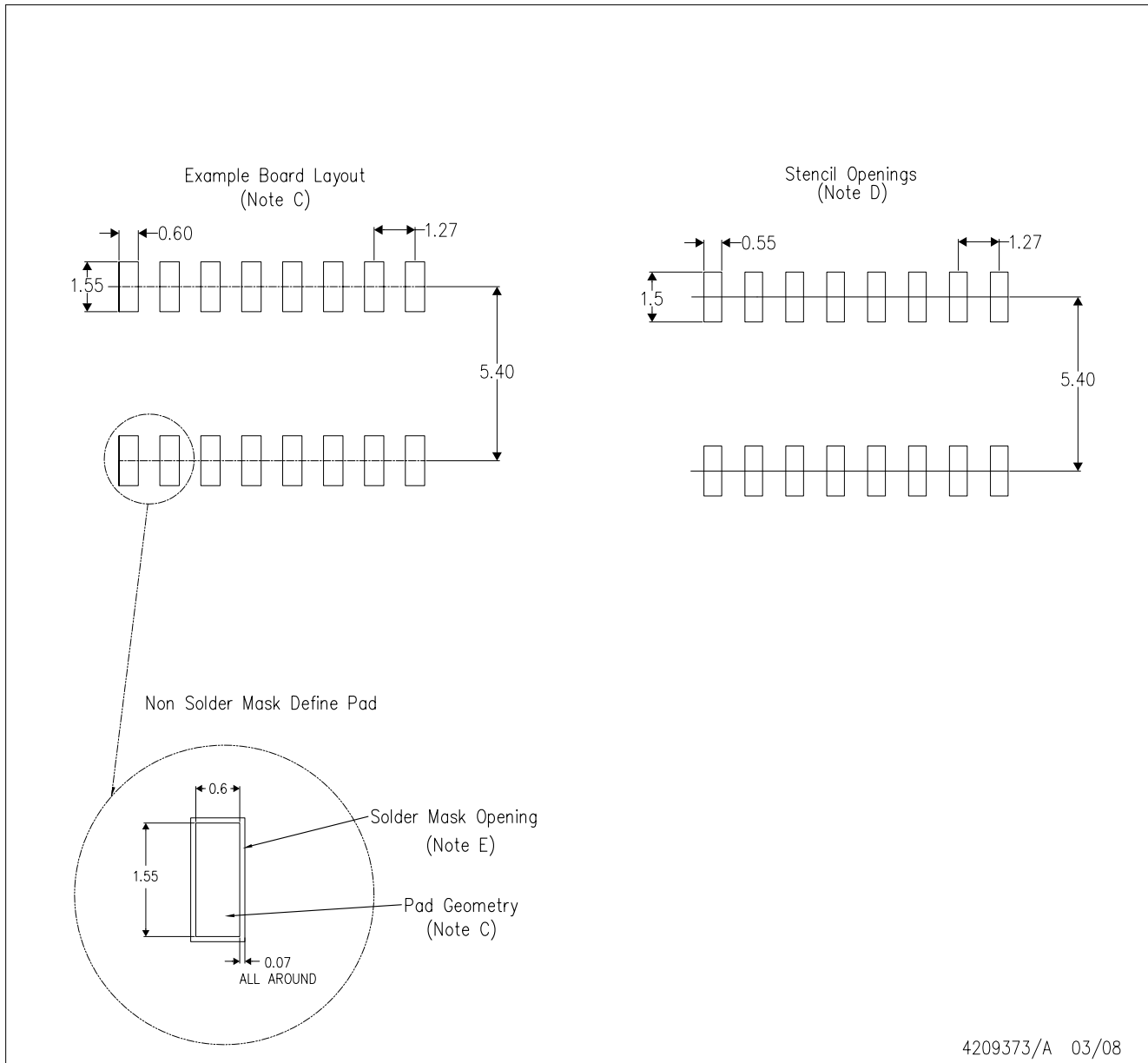


4040047-4/H 11/2006

## NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.

## D(R-PDSO-G16)



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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